Specification for Mono OLED Display module

1.13’’ Circular Mono OLED Display

Manufacturer	Truly Semiconductors Ltd
Part n˚	OEL9M1028-W-E
Ordering n˚	OEL9M1028-W-E
Customer Part n˚	n/a
Revision n˚	1.0
Issue Date	2016/03/03

Customer’s Approval

Company name	
Printed name	
Job title	
Signature	
Approval Stage:	This product is approved for the following production stage: - ☐ Sample / Prototype ☐ Pre-Production ☐ Mass Production
Approval Date	

Supplied by Anders Electronics plc
Manufactured by Truly Semiconductors Ltd

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SPECIFICATION

PART NO. : OEL9M1028-W-E

This specification maybe changed without any notice in order to improve performance or quality etc.
Please contact TRULY Semiconductors LTD. OLED R&D department for update specification and product status before design for this product or release the order.

PRODUCT CONTENTS

TRULY®信利		Customer	
Written by	ChenYongquan	Approved by	
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REVISION HISTORY

Rev.	Contents	Date
0.1	Preliminary Version.	2016-01-27
1.0	First release.	2016-03-02

■ PHYSICAL DATA

No.	Items:	Specification:	Unit
1	Diagonal Size	1.13	Inch
2	Resolution	128(H) x 128(V)	Dots
3	Active Area	28.80(W) x 28.80(H)	mm^2
4	Outline Dimension (Panel)	37.62 (W) x 41.31(H)	mm^2
5	Pixel Pitch	0.225(W) x 0.225(H)	mm^2
6	Pixel Size	0.205(W) x 0.205(H)	mm^2
7	Driver IC	SSD1327ZB	-
8	Display Color	White	-
9	Grayscale	4	Bit
10	Interface	Parallel/4-SPI/I^2C	-
11	IC package type	COG	-
12	Thickness	1.45 ± 0.1	mm
13	Weight	TBD	g
14	Duty	1/128	-

■ ABSOLUTE MAXIMUM RATINGS

Unless otherwise specified,(Voltage Referenced to V_{SS}) **(Ta = 25℃)**

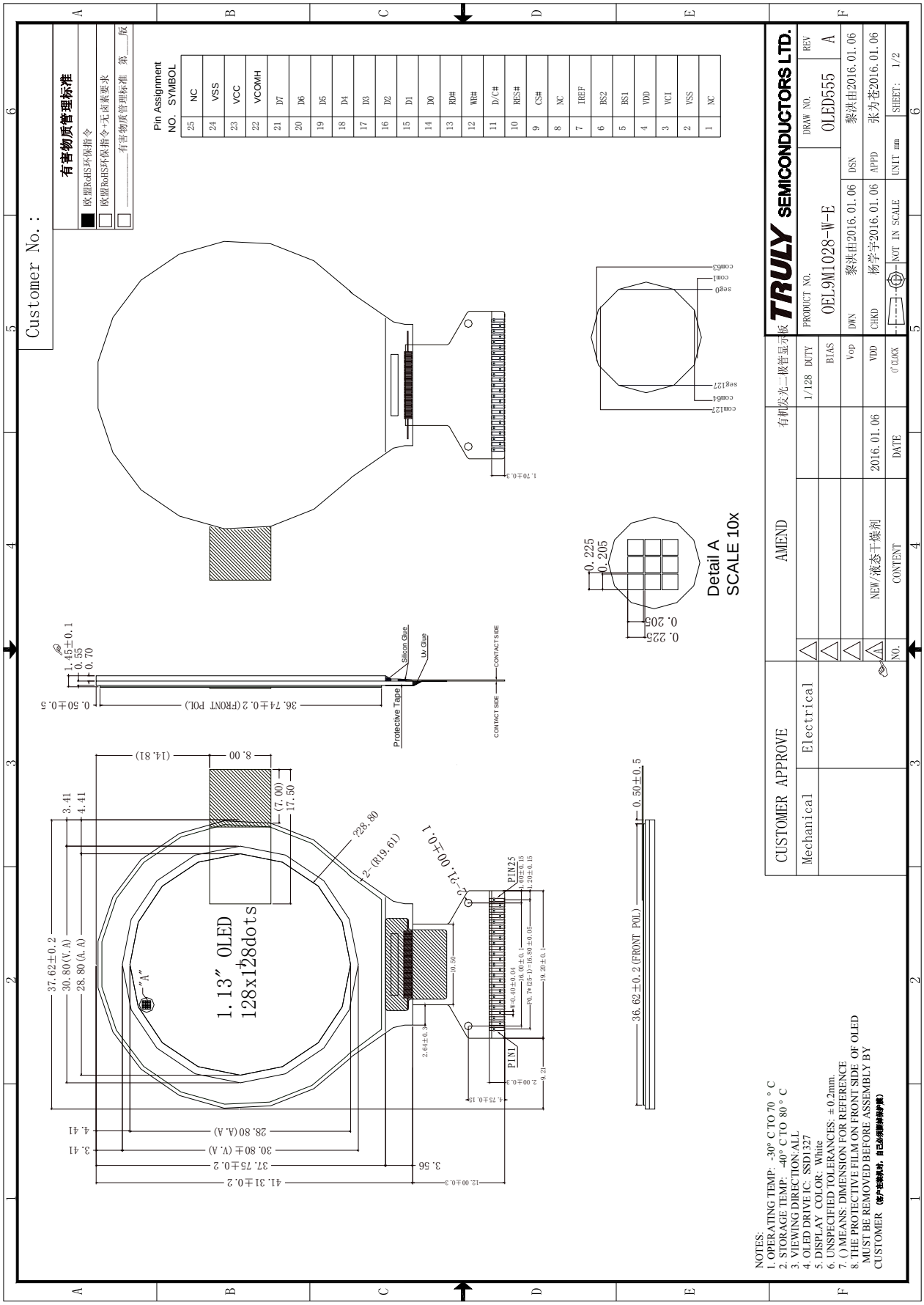
Items		Symbol	Min	Typ.	Max	Unit
Supply Voltage	Logic	V_{DD}	-0.5	-	2.75	V
	I/O	V_{CI}	-0.3		4.0	
	Driving	V_{CC}	-0.3	-	19.0	V
Operating Temperature		Top	-30	-	70	℃
Storage Temperature		Tst	-40	-	80	℃
Humidity		-	-	-	90	%RH

NOTE:

Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded.

Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

■ EXTERNAL DIMENSIONS



■ ELECTRICAL CHARACTERISTICS

◆DC Characteristics

Condition(Unless otherwise specified): Voltage referenced to VSS V_{CI}=2.6V to 3.5V Ta = 25℃

Items		Symbol	Min	Typ.	Max	Unit
Supply Voltage	Logic	V_{DD}	1.65	-	2.6	V
	I/O	V_{CI}	1.65	3.0	3.5	
	Operating	V_{CC}	8.0	15.0	18.0	V
Input Voltage	High Voltage	V_{IH}	0.8 x V_{CI}	-	V_{CI}	V
	Low Voltage	V_{IL}	VSS	-	0.2 x V_{CI}	V
Output Voltage	High Voltage	V_{OH}	0.8 x V_{CI}	-	V_{CI}	V
	Low Voltage	V_{OL}	VSS	-	0.2 x V_{CI}	V

◆AC Characteristics

1. 6800 parallel Interface Timing Characteristics

6800-Series MCU Parallel Interface Timing Characteristics

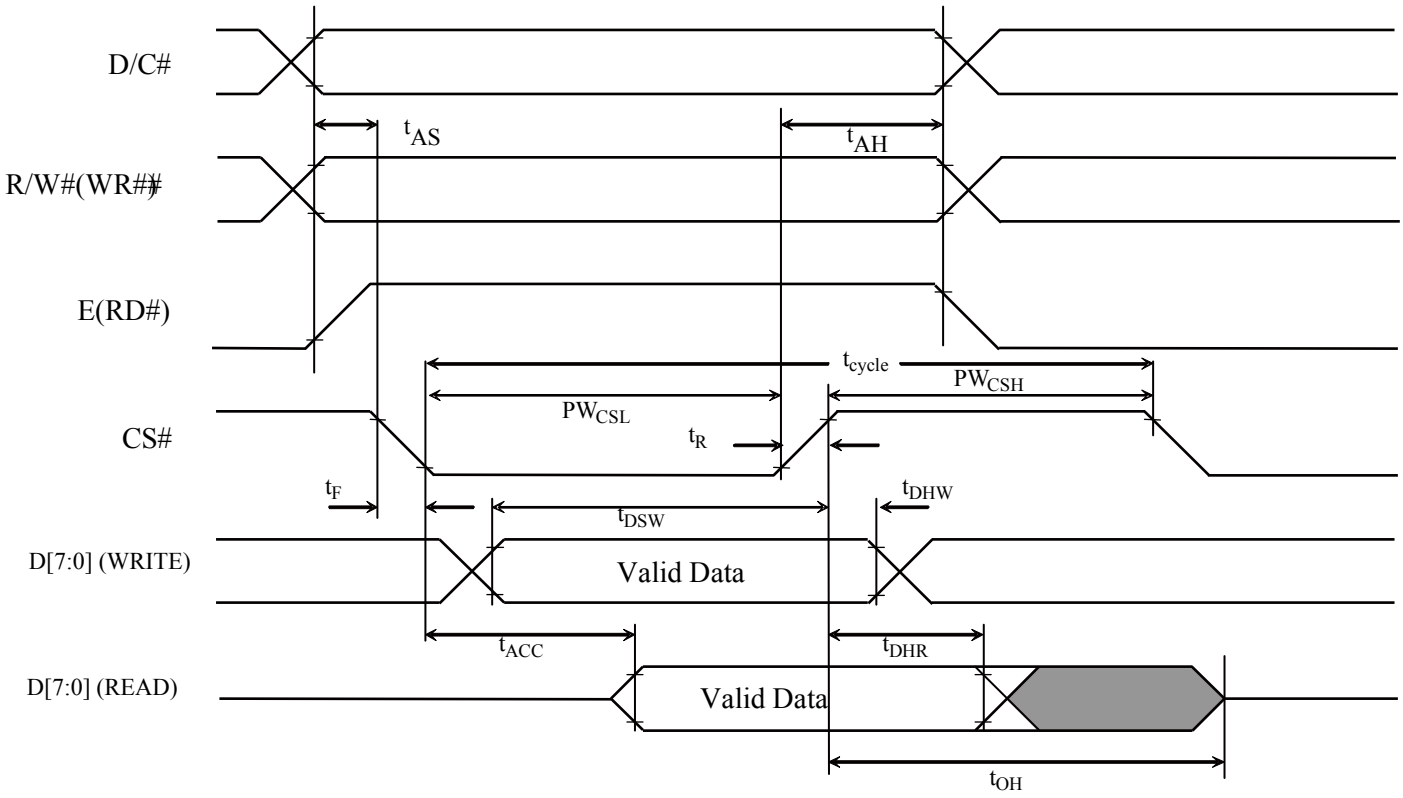
V_{CI} - V_{SS} = 1.65V to 2.1V (T_A = 25°C)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	10	-	-	ns
t_{AH}	Address Hold Time	0	-	-	ns
t_{DSW}	Write Data Setup Time	40	-	-	ns
t_{DHW}	Write Data Hold Time	44	-	-	ns
t_{DHR}	Read Data Hold Time	20	-	-	ns
t_{OH}	Output Disable Time	-	-	70	ns
t_{ACC}	Access Time	-	-	250	ns
PW_{CSL}	Chip Select Low Pulse Width (read) Chip Select Low Pulse Width (write)	120 60	-	-	ns
PW_{CSH}	Chip Select High Pulse Width (read) Chip Select High Pulse Width (write)	60 60	-	-	ns
t_R	Rise Time	-	-	15	ns
t_F	Fall Time	-	-	15	ns

V_{CI} - V_{SS} = 2.1V to 3.5V (T_A = 25°C)

Symbol	**Parameter**	**Min**	**Typ**	**Max**	**Unit**
t_{cycle}	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	10	-	-	ns
t_{AH}	Address Hold Time	0	-	-	ns
t_{DSW}	Write Data Setup Time	40	-	-	ns
t_{DHW}	Write Data Hold Time	20	-	-	ns
t_{DHR}	Read Data Hold Time	20	-	-	ns
t_{OH}	Output Disable Time	-	-	70	ns
t_{ACC}	Access Time	-	-	140	ns
PW_{CSL}	Chip Select Low Pulse Width (read) Chip Select Low Pulse Width (write)	120 60	-	-	ns
PW_{CSH}	Chip Select High Pulse Width (read) Chip Select High Pulse Width (write)	60 60	-	-	ns
t_R	Rise Time	-	-	15	ns
t_F	Fall Time	-	-	15	ns

6800-series MCU parallel interface characteristics



2. 8080 parallel Interface Timing Characteristics

8080-Series MCU Parallel Interface Timing Characteristics

V_{CI} - V_{SS} = 1.65V to 2.1V (T_A = 25°C)

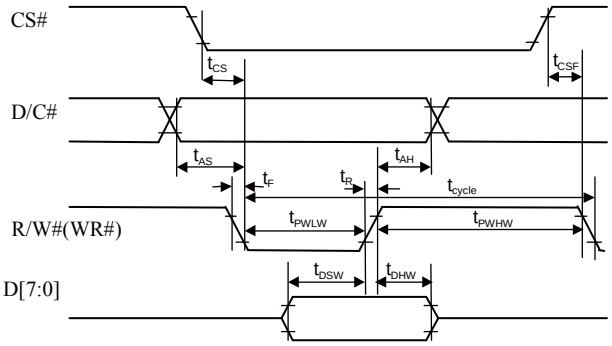
Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	30	-	-	ns
t_{AH}	Address Hold Time	0	-	-	ns
t_{DSW}	Write Data Setup Time	20	-	-	ns
t_{DHW}	Write Data Hold Time	42	-	-	ns
t_{DHR}	Read Data Hold Time	20	-	-	ns
t_{OH}	Output Disable Time	-	-	70	ns
t_{ACC}	Access Time	-	-	140	ns
t_{PWLR}	Read Low Time	150	-	-	ns
t_{PWLW}	Write Low Time	60	-	-	ns
t_{PWHR}	Read High Time	60	-	-	ns
t_{PWHW}	Write High Time	60	-	-	ns
t_R	Rise Time	-	-	15	ns
t_F	Fall Time	-	-	15	ns
t_{CS}	Chip select setup time	0	-	-	ns
t_{CSH}	Chip select hold time to read signal	0	-	-	ns
t_{CSF}	Chip select hold time	20	-	-	ns

V_{CI} - V_{SS} = 2.1V to 3.5V (T_A = 25°C)

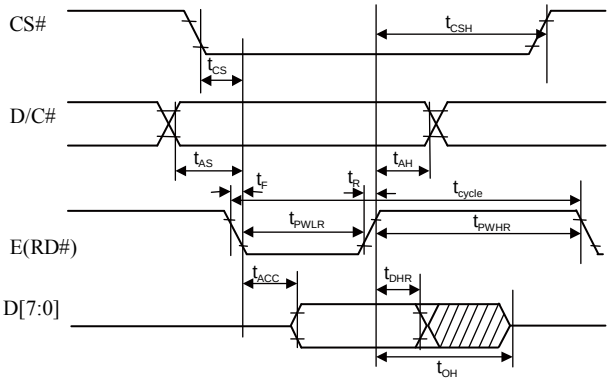
Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	18	-	-	ns
t_{AH}	Address Hold Time	0	-	-	ns
t_{DSW}	Write Data Setup Time	14	-	-	ns
t_{DHW}	Write Data Hold Time	20	-	-	ns
t_{DHR}	Read Data Hold Time	20	-	-	ns
t_{OH}	Output Disable Time	-	-	70	ns
t_{ACC}	Access Time	-	-	140	ns
t_{PWLR}	Read Low Time	150	-	-	ns
t_{PWLW}	Write Low Time	60	-	-	ns
t_{PWHR}	Read High Time	60	-	-	ns
t_{PWHW}	Write High Time	60	-	-	ns
t_R	Rise Time	-	-	15	ns
t_F	Fall Time	-	-	15	ns
t_{CS}	Chip select setup time	0	-	-	ns
t_{CSH}	Chip select hold time to read signal	0	-	-	ns
t_{CSF}	Chip select hold time	20	-	-	ns

8080-series MCU parallel interface characteristics

Write cycle



Read cycle



3. 4-SPI Interface Timing Characteristics

Serial Interface Timing Characteristics (4-wire SPI)

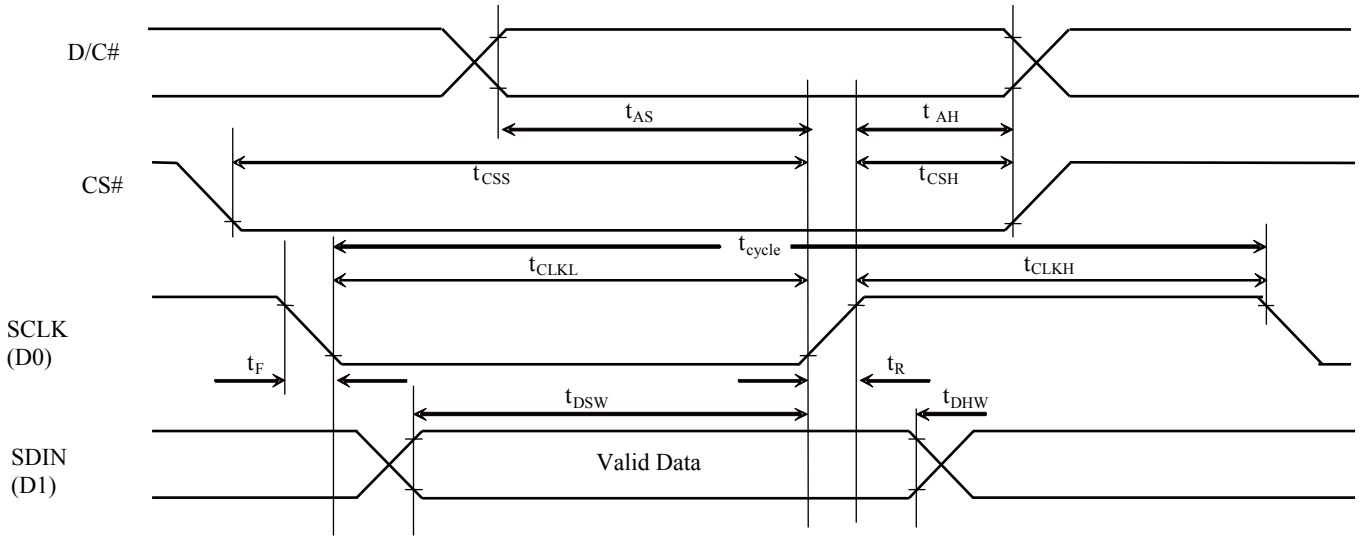
V_{CI} - V_{SS} = 1.65V to 2.1V (T_A = 25°C)

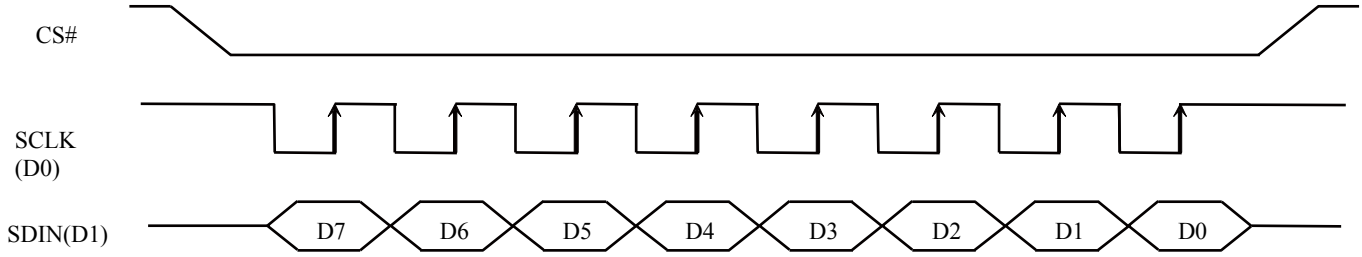
Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	220	-	-	ns
t_{AS}	Address Setup Time	15	-	-	ns
t_{AH}	Address Hold Time	15	-	-	ns
t_{CSS}	Chip Select Setup Time	20	-	-	ns
t_{CSH}	Chip Select Hold Time	10	-	-	ns
t_{DSW}	Write Data Setup Time	15	-	-	ns
t_{DHW}	Write Data Hold Time	30	-	-	ns
t_{CLKL}	Clock Low Time	25	-	-	ns
t_{CLKH}	Clock High Time	20	-	-	ns
t_R	Rise Time	-	-	15	ns
t_F	Fall Time	-	-	15	ns

V_{CI} - V_{SS} = 2.1V to 3.5V (T_A = 25°C)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	160	-	-	ns
t_{AS}	Address Setup Time	15	-	-	ns
t_{AH}	Address Hold Time	15	-	-	ns
t_{CSS}	Chip Select Setup Time	20	-	-	ns
t_{CSH}	Chip Select Hold Time	10	-	-	ns
t_{DSW}	Write Data Setup Time	15	-	-	ns
t_{DHW}	Write Data Hold Time	15	-	-	ns
t_{CLKL}	Clock Low Time	20	-	-	ns
t_{CLKH}	Clock High Time	20	-	-	ns
t_R	Rise Time	-	-	15	ns
t_F	Fall Time	-	-	15	ns

Serial interface characteristics (4-wire SPI)





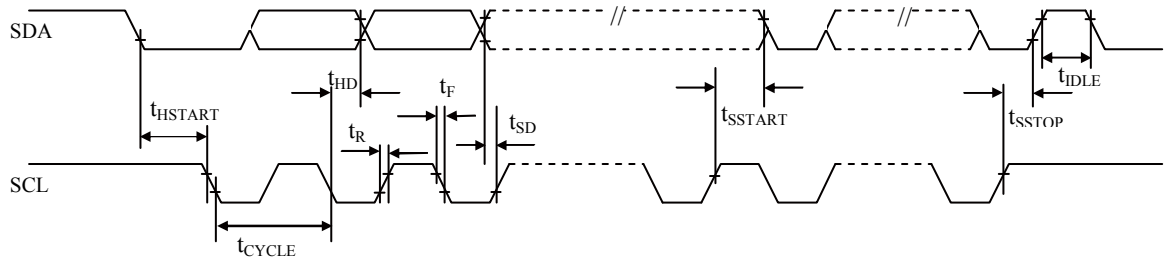
4 I²C Interface Timing Characteristics

I²C Interface Timing Characteristics

(V_{CI} - V_{SS} = 1.65V to 3.5V, T_A = 25°C)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	2.5	-	-	us
t_{HSTART}	Start condition Hold Time	0.6	-	-	us
t_{HD}	Data Hold Time (for "SDA_{OUT}" pin)	0	-	-	ns
	Data Hold Time (for "SDA_{IN}" pin)	300	-	-	ns
t_{SD}	Data Setup Time	100	-	-	ns
t_{SSTART}	Start condition Setup Time (Only relevant for a repeated Start condition)	0.6	-	-	us
t_{SSTOP}	Stop condition Setup Time	0.6	-	-	us
t_R	Rise Time for data and clock pin	-	-	300	ns
t_F	Fall Time for data and clock pin	-	-	300	ns
t_{IDLE}	Idle Time before a new transmission can start	1.3	-	-	us

I²C interface Timing characteristics

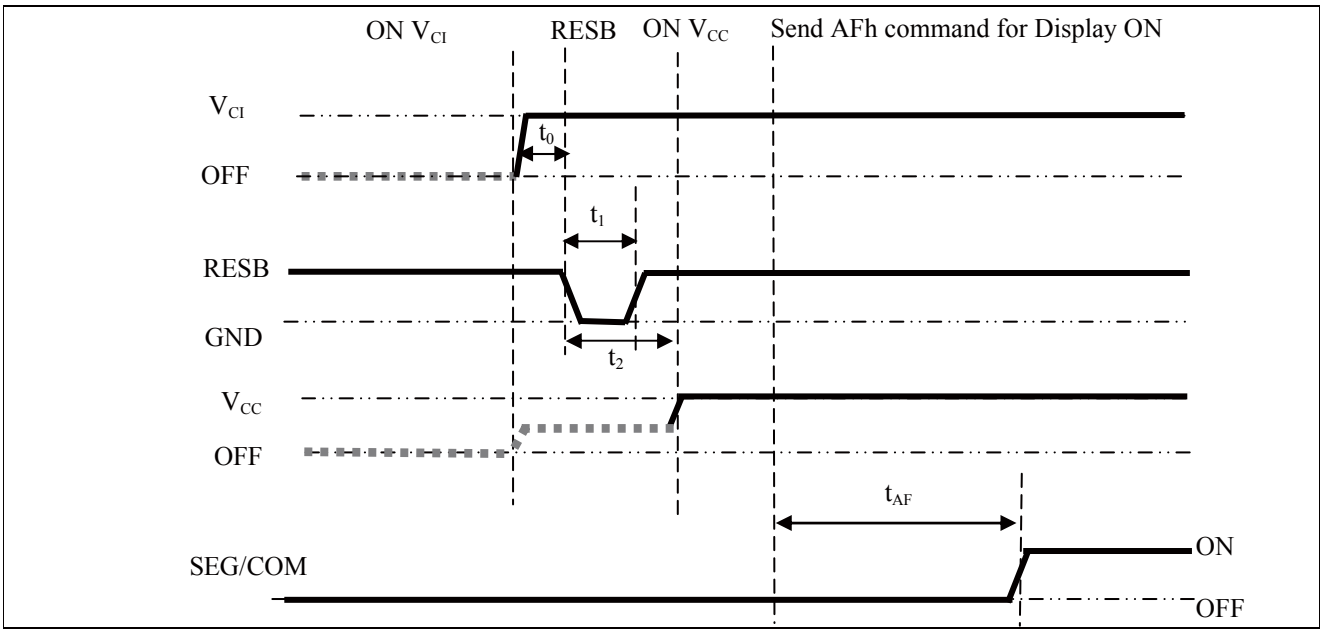


■ TIMING OF POWER SUPPLY

Power ON sequence:

1. Power ON $V_{CI.}$
2. After V_{CI} becomes stable, set wait time at least 1ms (t_0) for internal V_{DD} become stable. Then set RESB pin LOW (logic low) for at least 100us (t_1) [4] and then HIGH (logic high).
3. After set RESB pin LOW (logic low), wait for at least 100us (t_2). Then Power ON $V_{CC.}$[1]
4. After V_{CC} become stable, send command AFh for display ON. SEG/COM will be ON after 200ms (t_{AF}).
5. After V_{CI} become stable, wait for at least 300ms to send command.

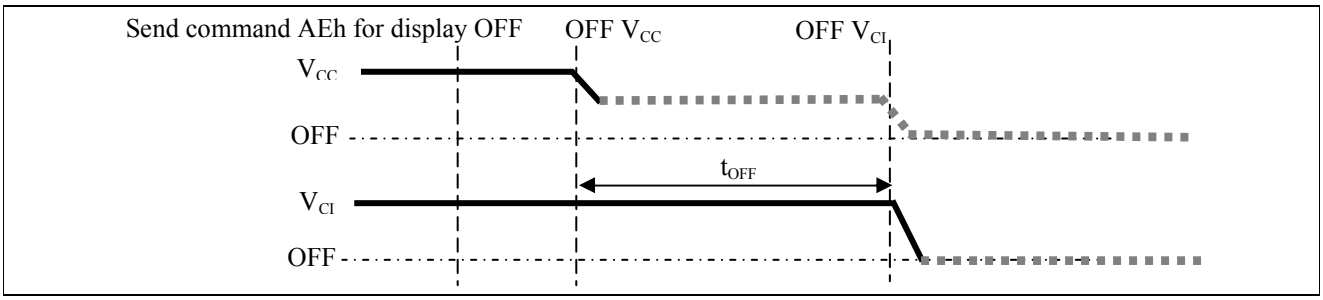
The Power ON sequence.



Power OFF sequence:

1. Send command AEh for display OFF.
2. Power OFF $V_{CC.}$[1], [2], [3]
3. Wait for t_{OFF}. Power OFF $V_{CI.}$ (where Minimum t_{OFF}=0ms [5], Typical t_{OFF}=100ms)

The Power OFF sequence



Note:

[1] Since an ESD protection circuit is connected between V_{CI} and V_{CC}, V_{CC} becomes lower than V_{CI} whenever V_{CI} is ON and V_{CC} is OFF as shown in the dotted line of V_{CC} in Figure above.

[2] V_{CC} should be kept float (disable) when it is OFF.

[3] Power pins (V_{CI}, V_{CC}) can never be pulled to ground under any circumstance.

[4] The register values are reset after t_1.

[5] V_{CI} should not be Power OFF before V_{CC} Power OFF.

■ ELECTRO-OPTICAL CHARACTERISTICS (Ta=25℃)

Items		Symbol	Min.	Typ.	Max.	Unit	Remark
Operating Luminance		L	80	100	-	cd /m^2	100% pixels ON
Power Consumption		P	-	300	400	mW	30% pixels ON
Frame Frequency		Fr	-	105	-	Hz	-
Color Coordinate	White	CIE x	0.25	0.29	0.33	CIE1931	Darkroom
		CIE y	0.29	0.33	0.37		
Response Time	Rise	Tr	-	-	0.02	ms	-
	Decay	Td	-	-	0.02	ms	-
Contrast Ratio		Cr	5000:1	-	-	-	Darkroom
Viewing Angle		△ θ	160	-	-	Degree	-
Operating Life Time		Top	20,000	-	-	Hours	L=100cd/m^2

Note:

1. **L=100 cd/m2** is based on VCI=3.0V ,VCC=15.0V, contrast command setting 0xDF;
2. Contrast ratio is defined as follows:

$$\text{Contrast ratio} = \frac{\text{Photo – detector output with OLED being “white”}}{\text{Photo – detector output with OLED being “black”}}$$

3. Life Time is defined when the Luminance has decayed to less than 50% of the initial Luminance specification. (Odd and even chess board alternately displayed)
   (The initial value should be closed to the typical value after adjusting.)

■ INTERFACE PIN CONNECTIONS

<table>
<tr><th>No.</th><th>Symbol</th><th>Description</th></tr>
<tr><td>1</td><td>NC</td><td>No connection.</td></tr>
<tr><td>2</td><td>VSS</td><td>Ground.</td></tr>
<tr><td>3</td><td>VCI</td><td>Low voltage power supply and power supply for interface logic level. It should match with the MCU interface voltage level and must be connected to external source.
VCI must always set to be equivalent to or higher than VDD.</td></tr>
<tr><td>4</td><td>VDD</td><td>Power supply pin for core logic operation.
VDD is regulated internally from VCI.
A capacitor should be connected between VDD and VSS.</td></tr>
<tr><td>5</td><td>BS1</td><td rowspan="2">MCU bus interface selection pins. Select appropriate logic setting as described in the following table.
<table>
<tr><td>BS[2:1]</td><td>Interface</td></tr>
<tr><td>00</td><td>4 line SPI</td></tr>
<tr><td>01</td><td>IIC</td></tr>
<tr><td>11</td><td>8-bit 8080 parallel</td></tr>
<tr><td>10</td><td>8-bit 6800 parallel</td></tr>
</table>
</td></tr>
<tr><td>6</td><td>BS2</td></tr>
<tr><td>7</td><td>IREF</td><td>This pin is the segment output current reference pin.
A resistor should be connected between this pin and VSS to maintain the current around 10uA.</td></tr>
<tr><td>8</td><td>NC</td><td>No connection.</td></tr>
<tr><td>9</td><td>CS#</td><td>This pin is the chip select input connecting to the MCU.
The chip is enabled for MCU communication only when CS# is pulled LOW (active LOW).</td></tr>
<tr><td>10</td><td>RES#</td><td>This pin is reset signal input.
When the pin is pulled LOW, initialization of the chip is executed.
Keep this pin pull HIGH during normal operation.</td></tr>
<tr><td>11</td><td>D/C#</td><td>This pin is Data/Command control pin connecting to the MCU.
When the pin is pulled HIGH, the data at D[7:0] will be interpreted as data.
When the pin is pulled LOW, the data at D[7:0] will be transferred to a command register.
In I2C mode, this pin acts as SA0 for slave address selection.</td></tr>
<tr><td>12</td><td>WR#</td><td>This pin is read / write control input pin connecting to the MCU interface.
When 6800 interface mode is selected, this pin will be used as Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIGH and write mode when LOW.
When 8080 interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled LOW and the chip is selected.
When serial or I2C interface is selected, this pin must be connected to VSS.</td></tr>
</table>

13	RD#	This pin is MCU interface input. When 6800 interface mode is selected, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH and the chip is selected. When 8080 interface mode is selected, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I2C interface is selected, this pin must be connected to VSS.
14-21	D0-D7	These pins are bi-directional data bus connecting to the MCU data bus. Unused pins are recommended to tie LOW. When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1will be the serial data input: SDIN and D2 should be kept NC. When I2C mode is selected, D2, D1 should be tied together and serve as SDAout,SDAin in application and D0 is the serial clock input, SCL.
22	VCOMH	COM signal deselected voltage level. A capacitor should be connected between this pin and VSS. No external power supply is allowed to connect to this pin.
23	VCC	Power supply for panel driving voltage. This is also the most positive power voltage supply pin. It is supplied by external high voltage source.
24	VSS	Ground.
25	NC	No connection.

MCU interface assignment under different bus interface mode

Pin Name / Bus Interface	Data/Command Interface								Control Signal				
	D7	D6	D5	D4	D3	D2	D1	D0	E	R/W#	CS#	D/C#	RES#
8-bit 8080	D[7:0]								RD#	WR#	CS#	D/C#	RES#
8-bit 6800	D[7:0]								E	R/W#	CS#	D/C#	RES#
4-wire SPI	Tie LOW					NC	SDIN	SCLK	Tie LOW		CS#	D/C#	RES#
I^2C	Tie LOW					SDA_{OUT}	SDA_{IN}	SCL	Tie LOW			SA0	RES#

V_{DD} Regulator

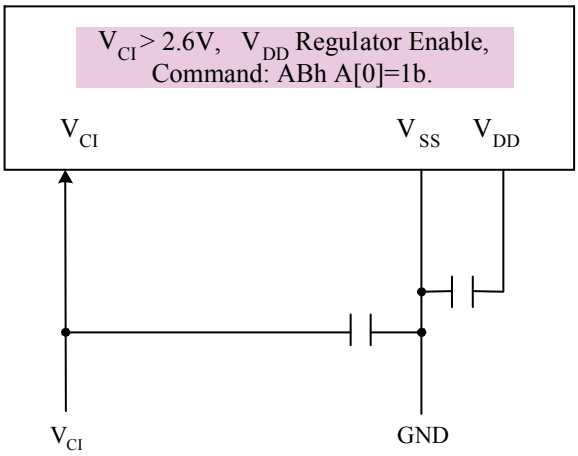
In SSD1327, the power supply pin for core logic operation, V_{DD}, can be supplied by external source or internally regulated through the V_{DD} regulator.

The internal V_{DD} regulator is enabled by setting bit A[0] to 1b in command ABh "Function Selection". V_{CI} should be larger than 2.6V when using the internal V_{DD} regulator. The typical regulated V_{DD} is about 2.5V

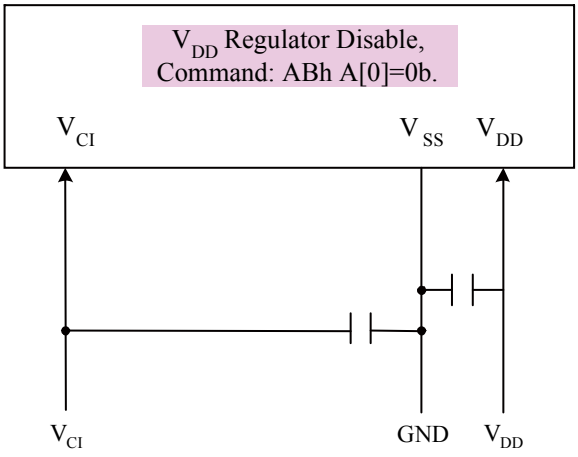
It should be notice that, no matter V_{DD} is supplied by external source or internally regulated; V_{CI} must always be set equivalent to or higher than V_{DD}.

The following figure shows the V_{DD} regulator pin connection scheme:

V_{CI} > 2.6V, V_{DD} regulator enable pin connection scheme



V_{DD} regulator disable pin connection scheme



No RAM access through MCU interface when there is no external / internal V_{DD}.

■ COMMAND TABLE

1. Fundamental Command Table											
D/C#	**Hex**	**D7**	**D6**	**D5**	**D4**	**D3**	**D2**	**D1**	**D0**	**Command**	**Description**
0 0 0	15 A[5:0] B[5:0]	0 * *	0 * *	0 A_5 A_5	1 A_4 A_4	0 A_3 A_3	1 A_2 A_2	0 A_1 A_1	1 A_0 A_0	Set Column Address	Setup Column start and end address A[5:0]: Start Address, range:00h~3Fh, (RESET = 00h) B[5:0]: End Address, range:00h~3Fh, (RESET = 3Fh)
0 0 0	75 A[6:0] B[6:0]	0 * *	0 A_6 A_6	0 A_5 A_5	1 A_4 A_4	0 A_3 A_3	1 A_2 A_2	0 A_1 A_1	1 A_0 A_0	Set Row Address	Setup Row start and end address A[6:0]: Start Address, range:00h~7Fh, (RESET = 00h) B[6:0]: End Address, range:00h~7Fh, (RESET = 7Fh)
0 0	81 A[7:0]	1 A_7	0 A_6	0 A_5	0 A_4	0 A_3	0 A_2	0 A_1	1 A_0	Set Contrast Control	Double byte command to select 1 out of 256 contrast steps. Contrast increases as the value increases. (RESET = 7Fh)
0	84 ~ 86	1	0	0	0	0	1	X_1	X_0	Reserved	Command for no operation
0 0	A0 A[7:0]	1 0	0 A_6	1 0	0 A_4	0 0	0 A_2	0 A_1	0 A_0	Set Re-map	Re-map setting in Graphic Display Data RAM (GDDRAM) A[0] = 0b, Disable Column Address Re-map (RESET) A[0] = 1b, Enable Column Address Re-map A[1] = 0b, Disable Nibble Re-map (RESET) A[1] = 1b, Enable Nibble Re-map A[2] = 0b, Enable Horizontal Address Increment (RESET) A[2] = 1b, Enable Vertical Address Increment A[3] = 0b, Reserved (RESET) A[4] = 0b, Disable COM Re-map (RESET) A[4] = 1b, Enable COM Re-map A[5] = 0b, Reserved (RESET) A[6] = 0b, Disable COM Split Odd Even (RESET) A[6] = 1b, Enable COM Split Odd Even A[7] = 0b, Reserved (RESET)
0 0	A1 A[6:0]	1 *	0 A_6	1 A_5	0 A_4	0 A_3	0 A_2	0 A_1	1 A_0	Set Display Start Line	A[6:0]: Vertical shift by setting the starting address of display RAM from 0 ~ 127 (RESET = 00h)

1. Fundamental Command Table											
D/C#	**Hex**	**D7**	**D6**	**D5**	**D4**	**D3**	**D2**	**D1**	**D0**	**Command**	**Description**
0 0	A2 A[6:0]	1 *	0 A_6	1 A_5	0 A_4	0 A_3	0 A_2	1 A_1	0 A_0	Set Display Offset	A[6:0]: Set vertical offset by COM from 0 ~ 127 (RESET = 00h) e.g. Set A[6:0] to 010000b to move COM16 towards COM0 direction for 16 row
0	A4 ~ A7	1	0	1	0	0	1	X_1	X_0	Set Display Mode	A4h = Normal display (RESET) A5h = All ON (All pixels have gray scale of 15, GS15) A6h = All OFF (All pixels have gray scale of 0, GS0) A7h = Inverse Display (GS0 → GS15, GS1 → GS14, GS2 → GS13, …)
0 0	A8 A[6:0]	1 *	0 A_6	1 A_5	0 A_4	1 A_3	0 A_2	0 A_1	0 A_0	Set MUX Ratio	A[6:0]: Set MUX ratio from 16MUX ~ 128MUX: A[6:0] = 15 represents 16MUX A[6:0] = 16 represents 17MUX : A[6:0] = 126 represents 127MUX A[6:0] = 127 represents 128MUX (RESET) It should be noted that A[6:0]=0~14 is not allowed
0 0	AB A[0]	1 0	0 0	1 0	0 0	1 0	0 0	1 0	1 A_0	Function Selection A	A[0]=0b, Select external V_{DD} (i.e. Disable internal V_{DD} regulator) A[0]=1b, Enable internal V_{DD} regulator (RESET)
0	AE / AF	1	0	1	0	1	1	1	X_0	Set Display ON/OFF	AEh = Display OFF (sleep mode) (RESET) AFh = Display ON in normal mode
0 0	B1 A[7:0]	1 A_7	0 A_6	1 A_5	1 A_4	0 A_3	0 A_2	0 A_1	1 A_0	Set Phase Length	A[3:0]: Phase 1 period of 1~15 DCLK's e.g. A[3:0] = 1111b, 15 DCLK Clock (RESET = 0100b) A[7:4]: Phase 2 period of 1~15 DCLK's e.g. A[7:4] = 1111b, 15 DCLK Clocks (RESET = 0111b) **Note** (1) 0 DCLK is invalid in phase 1 & phase 2 (2) GS15 level pulse width must be set larger than the period of phase 1 + phase 2
0	B2	1	0	1	1	0	0	1	0	NOP	Command for no operation

1. Fundamental Command Table											
D/C#	**Hex**	**D7**	**D6**	**D5**	**D4**	**D3**	**D2**	**D1**	**D0**	**Command**	**Description**
0 0	B3 A[7:0]	1 A_7	0 A_6	1 A_5	1 A_4	0 A_3	0 A_2	1 A_1	1 A_0	Set Front Clock Divider /Oscillator Frequency	A[3:0]: Define divide ratio (D) of display clock (DCLK) Divide ratio=A[3:0]+1 (RESET is 0000b, i.e. divide ratio = 1) A[7:4]: Set the Oscillator Frequency, F_{OSC}. Oscillator Frequency increases with the value of A[7:4] and vice versa. (Range:0000b~1111b) (RESET = 0000b)
0 0	B5 A[1:0]	1 0	0 0	1 0	1 0	0 0	1 0	0 A_1	1 A_0	GPIO	A[1:0] = 00b represents GPIO pin HiZ, input disable (always read as low) A[1:0] = 01b represents GPIO pin HiZ, input enable A[1:0] = 10b represents GPIO pin output Low (RESET) A[1:0] = 11b represents GPIO pin output High
0 0	B6 A[3:0]	1 *	0 *	1 *	1 *	0 A_3	1 A_2	1 A_1	0 A_0	Set Second pre-charge Period	A[3:0]: Second Pre-charge period of 1~15 DCLK's e.g. A[3:0] = 1111b, 15 DCLK Clock (RESET = 0100b) **Note** (1) This command is used to adjust the second pre-charge period after enabling the second pre-charge by setting A[1] = 1b in command D5h
0 0 0 … … … 0 0	B8 A1[5:0] A2[5:0] … … … A14[5:0] A15[5:0]	1 * * … … … * *	0 * * … … … * *	1 $A1_5$ $A2_5$ … … … $A14_5$ $A15_5$	1 $A1_4$ $A2_4$ … … … $A14_4$ $A15_4$	1 $A1_3$ $A2_3$ … … … $A14_3$ $A15_3$	0 $A1_2$ $A2_2$ … … … $A14_2$ $A15_2$	0 $A1_1$ $A2_1$ … … … $A14_1$ $A15_1$	0 $A1_0$ $A2_0$ … … … $A14_0$ $A15_0$	Set Gray Scale Table	The next 15 data bytes set the gray scale pulse width in unit of DCLK's. A1[5:0], value for GS1 level Pulse width A2[5:0], value for GS2 level Pulse width … A14[5:0], value for GS14 level Pulse width A15[5:0], value for GS15 level Pulse width **Note** (1) The pulse width value of GS1, GS2, ... , GS15 should not be equal. i.e. 0<GS1<GS2 … <GS15 (2) GS15 level pulse width must be set larger than the period of phase 1 + phase 2
0	B9	1	0	1	1	1	0	0	1	Linear LUT	The default Linear Gray Scale table is set in unit of DCLK's as follow GS0 level pulse width = 0; GS1 level pulse width = 0; GS2 level pulse width = 2; GS3 level pulse width = 4; : : GS14 level pulse width = 26; GS15 level pulse width = 28

1. Fundamental Command Table

D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	BB	1	0	1	1	1	0	1	1	NOP	Command for no operation
0 0	BC A[3:0]	1 0	0 0	1 0	1 0	1 A_3	1 A_2	0 A_1	0 A_0	Set Pre-charge voltage	Set pre-charge voltage level. A[3:0] / Hex code / Pre-charge voltage 0000 / 00h / 0.20 x V_{CC} : / : / : 0101 / 05h / 0.5 x V_{CC} (RESET) : / : / : 0111 / 07h / 0.613 x V_{CC} 1xxx / 08h / V_{COMH}
0 0	BE A[2:0]	1 0	0 0	1 0	1 0	1 0	1 A_2	1 A_1	0 A_0	Set V_{COMH}	Set COM deselect voltage level. A[2:0] / Hex code / V_{COMH} 000 / 00h / 0.72 x V_{CC} : / : / : 101 / 05h / 0.82 x V_{CC} (RESET) : / : / : 111 / 07h / 0.86 x V_{CC}
0 0	D5 A[2:0]	1 0	1 1	0 1	1 0	0 0	1 0	0 A_1	1 A_0	Function Selection B	A[1] = 0b: Disable second precharge (RESET) A[1] = 1b: Enable second precharge A[0] = 0b: Internal VSL (RESET) A[0] = 1b: Enable external VSL **Note** (1) Refer to Table 6-1 for VSL pin details
0 0	FD A[2]	1 0	1 0	1 0	1 1	1 0	1 A_2	0 1	1 0	Set Command Lock	A[2]: MCU protection status. A[2] = 0b, Unlock OLED driver IC MCU interface from entering command (RESET) A[2] = 1b, Lock OLED driver IC MCU interface from entering command **Note** (1) The locked OLED driver IC MCU interface prohibits all commands and memory access except the FDh command

Note: *Do not use any other commands, or the system malfunction may result.

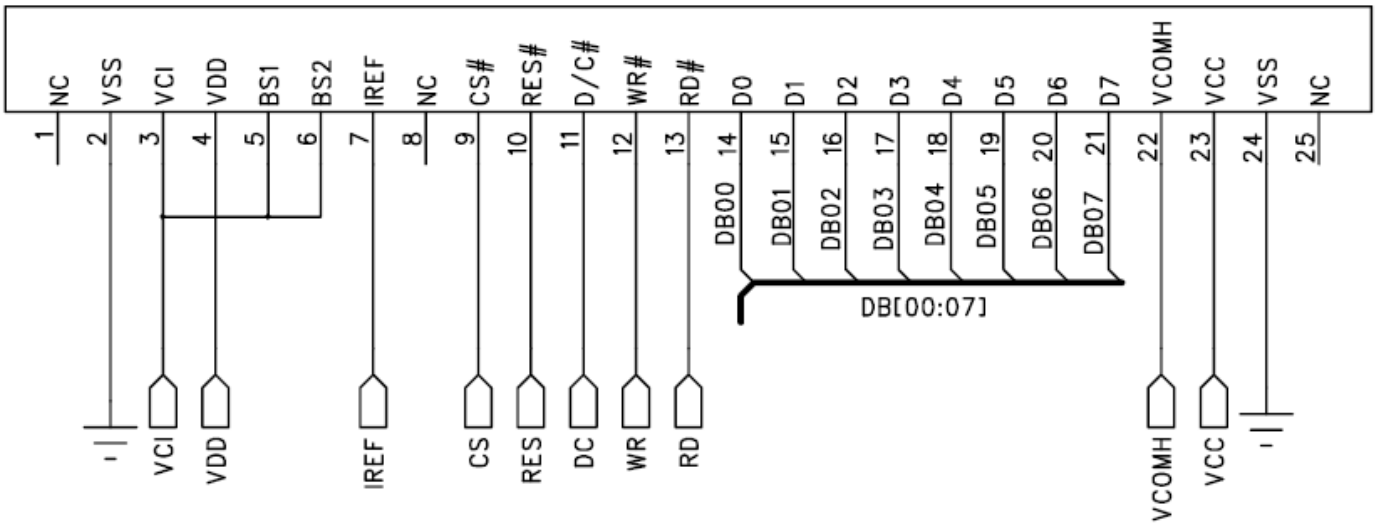
■ INITIALIZATION CODE

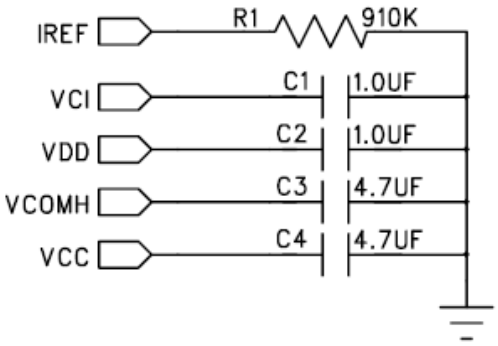
```
void Init_SSD1327(void)
{
    Write_Command(0XFD);            //Set Command Lock
    Write_Command(0X12);            //(12H=Unlock,16H=Lock)

    Write_Command(0XAE);            //Display OFF(Sleep Mode)

    Write_Command(0XB3);            //Display Clock Divider
    Write_Command(0X50);

    Write_Command(0XA8);            //Set Multiplex Ratio
    Write_Command(0X7F);

    Write_Command(0X15);            //Set Column Address
    Write_Command(S_COL);           //Start Column Address
    Write_Command(E_COL);           //End Column Address

    Write_Command(0X75);            //Set Row Address
    Write_Command(S_ROW);           //Start Row Address
    Write_Command(E_ROW);           //End Row Address

    Write_Command(0X81);            //Set Contrast
    Write_Command(CONTRAST);

    Write_Command(0XA0);            //Set Remap
    Write_Command(0X40);

    Write_Command(0XA1);            //Set Display Start Line
    Write_Command(0X00);

    Write_Command(0XA2);            //Set Display Offset
    Write_Command(0X00);

    Write_Command(0XA4);            //Normal Display

    Write_Command(0XAB);            //Set VDD regulator
    Write_Command(0X01);            //Regulator Enable

    Write_Command(0XB1);            //Set Phase Length
    Write_Command(0X22);

    Write_Command(0XD5);            //Set second precharge and VSL
    Write_Command(0X62);

    Write_Command(0XB6);            //Set Second precharge Period
    Write_Command(0X0A);

//  Write_Command(0XB9);            //Set Linear LUT

    Write_Command(0xB8);
    Write_Command(0x02);
    Write_Command(0x04);
    Write_Command(0x07);
    Write_Command(0x0B);
    Write_Command(0x0F);
    Write_Command(0x13);
    Write_Command(0x17);
    Write_Command(0x1C);
```

```
    Write_Command(0x20);
    Write_Command(0x25);
    Write_Command(0x2A);
    Write_Command(0x2F);
    Write_Command(0x35);
    Write_Command(0x3A);
    Write_Command(0x3F);

    Write_Command(0XBC);          //Set pre-charge voltage level
    Write_Command(0X10);          //VCOMH

    Write_Command(0XBE);          //Set COM deselect voltage level
    Write_Command(0X05);          //0.82*VCC

    Write_Command(0XAF);          //Display ON
}
```

■ SCHEMATIC EXAMPLE

◆8080 Series Interface Application Circuit(With internal VDD regulater):





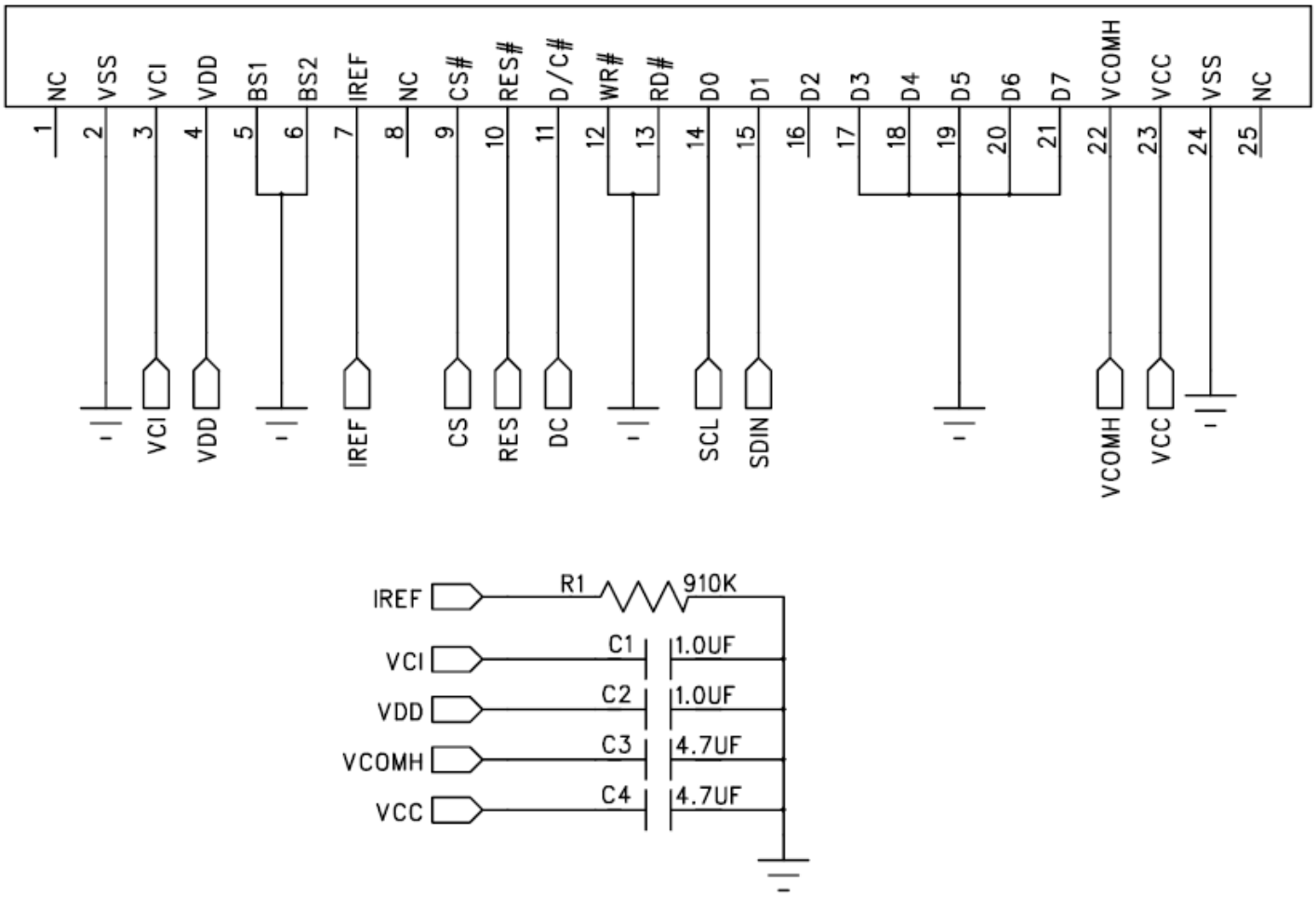
NOTE:

1.The VCOMH capacitor is recommended to use tantalum capacitor to reduce noise.

2. The capacitor and the resistor value are recommended value. Select the appropriate value against module application.

3. The VCI VCC should be connected to external power supply.

◆4-SPI Interface Application Circuit(With internal VDD regulater):



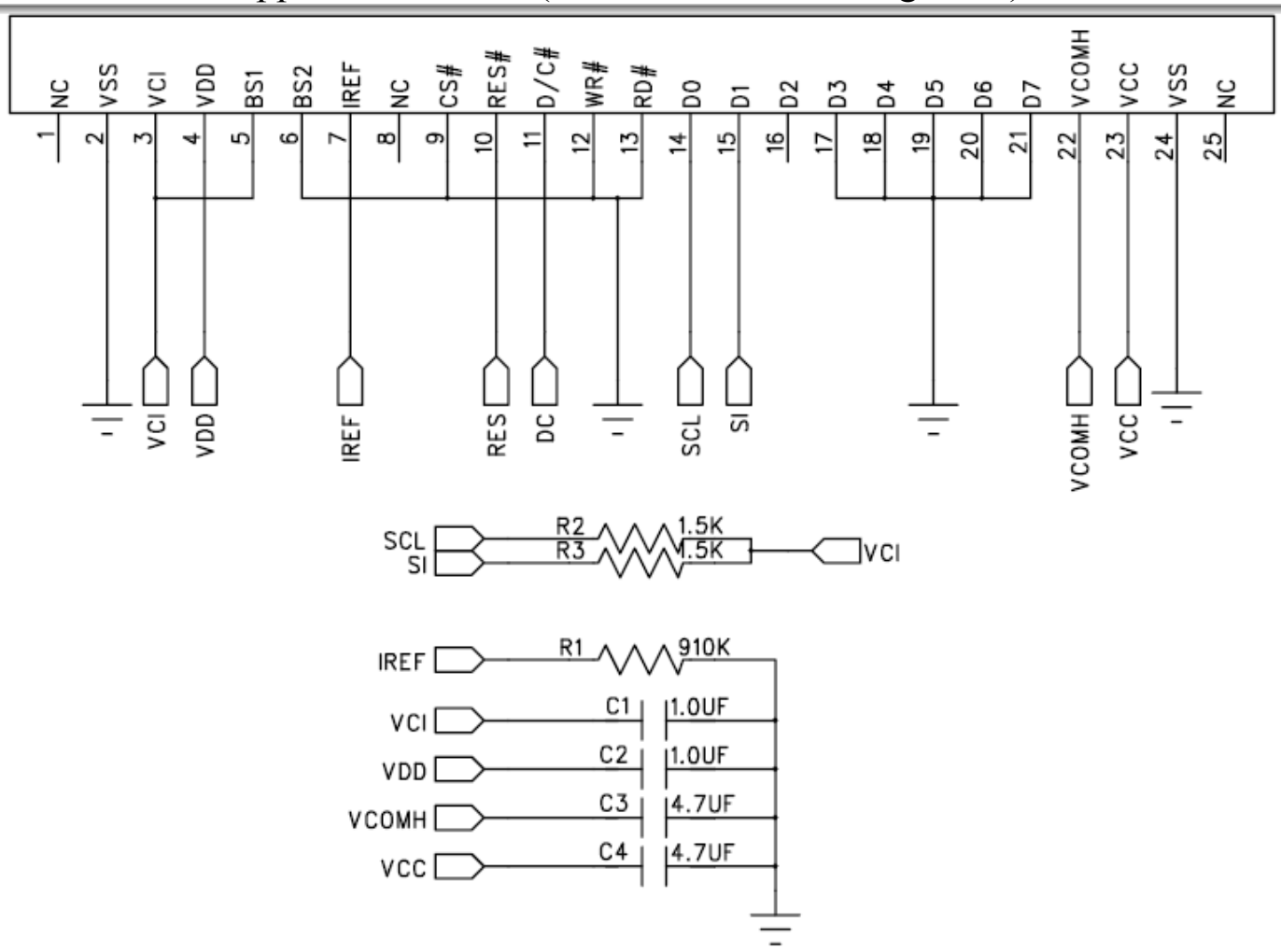
NOTE:

1.The VCOMH capacitor is recommended to use tantalum capacitor to reduce noise.

2. The capacitor and the resistor value are recommended value. Select the appropriate value against module application.

3. The VCI VCC should be connected to external power supply.

◆IIC Interface Application Circuit(With internal VDD regulater):



NOTE:

1.The VCOMH capacitor is recommended to use tantalum capacitor to reduce noise.

2. The capacitor and the resistor value are recommended value. Select the appropriate value against module application.

3. The VCI VCC should be connected to external power supply.

■ RELIABILITY TESTS

Item		Condition	Criterion
High Temperature Storage (HTS)		80±2℃, 200 hours	1. After testing, the function test is ok. 2. After testing, no addition to the defect. 3. After testing, the change of luminance should be within +/- 50% of initial value. 4. After testing, the change for the mono and area color must be within (+/-0.02, +/-0.02) and for the full color it must be within (+/-0.04, +/-0.04) of initial value based on 1931 CIE coordinates. 5. After testing, the change of total current consumption should be within +/- 50% of initial value.
High Temperature Operating (HTO)		70±2℃, 96 hours	
Low Temperature Storage (LTS)		-40±2℃, 200 hours	
Low Temperature Operating (LTO)		-30±2℃, 96 hours	
High Temperature / High Humidity Storage (HTHHS)		50±3℃, 90%±3%RH, 120 hours	
Thermal Shock (Non-operation) (TS)		-40±2℃ ~ 25℃ ~ 70±2℃ (30min) (5min) (30min) 10cycles	
Vibration (Packing)	10~55~10Hz,amplitude 1.5mm, 1 hour for each direction x, y, z	1. One box for each test. 2. No addition to the cosmetic and the electrical defects.	
Drop (Packing)	Height : 1 m, each time for 6 sides, 3 edges, 1 angle		
ESD (finished product housing)	±4kV (R: 330Ω C: 150pF , 10times, air discharge)	1. After testing, cosmetic and electrical defects should not happen. 2. In case of malfunction or defect caused by ESD damage, it would be judged as a good part if it would be recovered to normal state after resetting.	

Note： 1) For each reliability test, the sample quantity is 3, and only for one test item.
2) The HTHHS test is requested the Pure Water(Resistance＞10MΩ).
3) The test should be done after 2 hours of recovery time in normal environment.

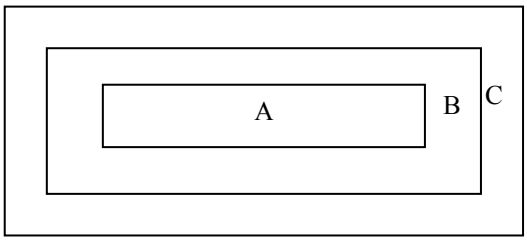
■ OUTGOING QUALITY CONTROL SPECIFICATION

◆Standard

According to GB/T2828.1-2003/ISO 2859-1：1999 and ANSI/ASQC Z1.4-1993, General Inspection Level II.

◆Definition

1 Major defect : The defect that greatly affect the usability of product.
2 Minor defect : The other defects, such as cosmetic defects, etc.
3 Definition of inspection zone:



Zone A: Active Area

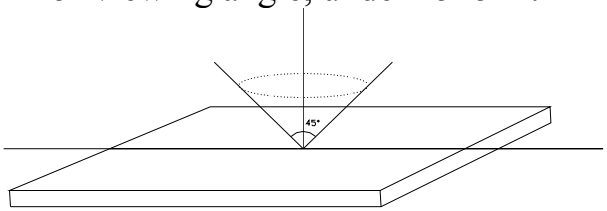
Zone B: Viewing Area except Zone A

Zone C: Outside Viewing Area

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of quality and assembly to customer`s product.

◆Inspection Methods

1 The general inspection : under 20W x 2 or 40W fluorescent light, about 30cm viewing distance, within 45º viewing angle, under 25±5℃.



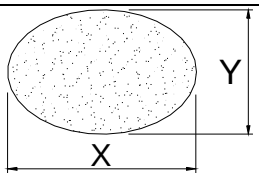
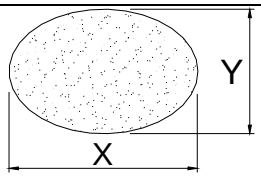
2 The luminance and color coordinate inspection : By PR705 or BM-7 or the equal equipments, in the dark room, under 25±5℃.

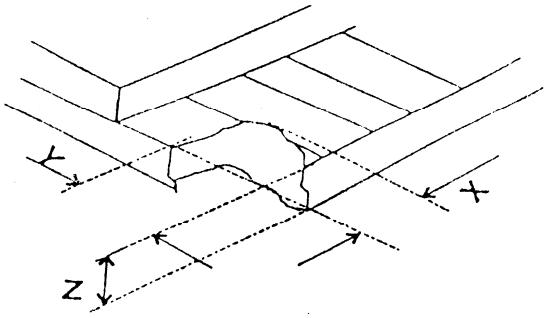
◆Inspection Criteria

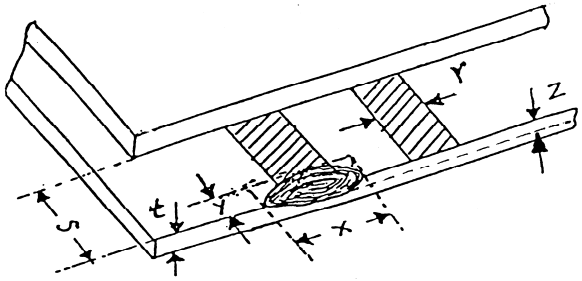
1 Major defect : AQL= 0.65

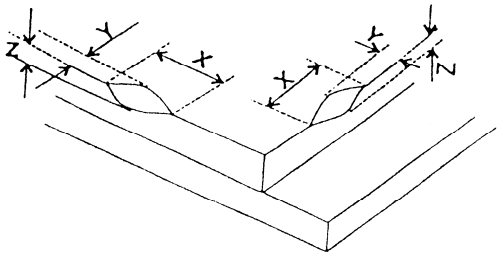
Item	Criterion
Function Defect	1. No display or abnormal display is not accepted
	2. Open or short is not accepted.
	3. Power consumption exceeding the spec is not accepted.
Outline Dimension	Outline dimension exceeding the spec is not accepted.
Glass Crack	Glass crack tends to enlarge is not accepted.

2 Minor Defect : AQL= 1.5

<table>
<tr><td>Item</td><td colspan="4">Criterion</td></tr>
<tr><td rowspan="5">Spot Defect (dimming and lighting spot)</td><td colspan="2" rowspan="2">Size (mm)</td><td colspan="2">Accepted Qty</td></tr>
<tr><td>Area A + Area B</td><td>Area C</td></tr>
<tr><td rowspan="3">  </td><td>Φ≦0.07</td><td colspan="2">Ignored</td></tr>
<tr><td>0.07＜Φ≦0.10</td><td>3</td><td rowspan="3">Ignored</td></tr>
<tr><td>0.10＜Φ≦0. 15</td><td>1</td></tr>
<tr><td colspan="4">Note : Φ= (x + y) / 2</td><td>0.15＜Φ</td><td>0</td></tr>
<tr><td rowspan="5">Line Defect (dimming and lighting line)</td><td>L (Length) : mm</td><td>W (Width) : mm</td><td>Area A + Area B</td><td>Area C</td></tr>
<tr><td>/</td><td>W≦0.02</td><td colspan="2">Ignored</td></tr>
<tr><td>L≦3.0</td><td>0.02＜W≦0.03</td><td>2</td><td rowspan="3">Ignored</td></tr>
<tr><td>L≦2.0</td><td>0.03＜W≦0.05</td><td>1</td></tr>
<tr><td>/</td><td>0.05＜W</td><td>As spot defect</td></tr>
<tr><td colspan="5">Remarks: The total of spot defect and line defect shall not exceed 4 pcs. The distance between two lines defects must exceed 1 mm</td></tr>
<tr><td>Polarizer Stain</td><td colspan="4">Stain which can be wiped off lightly with a soft cloth or similar cleaning is accepted, otherwise, according to the Spot Defect and the Line Defect.</td></tr>
<tr><td rowspan="8">Polarizer Scratch</td><td colspan="4">1. If scratch can be seen during operation, according to the criterions of the Spot Defect and the Line Defect.</td></tr>
<tr><td colspan="4">2. If scratch can be seen only under non-operation or some special angle, the criterion is as below :</td></tr>
<tr><td>L (Length) : mm</td><td>W (Width) : mm</td><td>Area A + Area B</td><td>Area C</td></tr>
<tr><td>/</td><td>W≦0.02</td><td colspan="2">Ignore</td></tr>
<tr><td>3.0＜L≦5.0</td><td>0.02＜W≦0.04</td><td>2</td><td rowspan="3">Ignore</td></tr>
<tr><td>L≦3.0</td><td>0.04＜W≦0.06</td><td>1</td></tr>
<tr><td>/</td><td>0.06＜W</td><td>0</td></tr>
<tr><td rowspan="5">Polarizer Air Bubble</td><td colspan="2">Size</td><td>Area A + Area B</td><td>Area C</td></tr>
<tr><td rowspan="4">  </td><td>Φ≦0.20</td><td colspan="2">Ignored</td></tr>
<tr><td>0.20＜Φ≦0.30</td><td>2</td><td rowspan="3">Ignored</td></tr>
<tr><td>0.30＜Φ≦0.50</td><td>1</td></tr>
<tr><td>0.50＜Φ</td><td>0</td></tr>
</table>

<table>
<tr><td rowspan="4">Glass Defect (Glass Chiped)</td><td>1. On the corner
(mm)
 

<table><tr><td>x</td><td>≤ 1.5</td></tr><tr><td>y</td><td>≤ 1.5</td></tr><tr><td>z</td><td>≤ t</td></tr></table></td></tr>
<tr><td>2. On the bonding edge
(mm)
 

<table><tr><td>x</td><td>≤ a / 4</td></tr><tr><td>y</td><td>≤ s / 3 &≤0.7</td></tr><tr><td>z</td><td>≤ t</td></tr></table></td></tr>
<tr><td>3. On the other edges
(mm)
 

<table><tr><td>x</td><td>≤ a / 8</td></tr><tr><td>y</td><td>≤ 0.7</td></tr><tr><td>z</td><td>≤ t</td></tr></table></td></tr>
<tr><td>Note: t: glass thickness ; s: pad width ; a: the length of the edge</td></tr>
<tr><td>TCP Defect</td><td>Crack, deep fold and deep pressure mark on the TCP are not accepted</td></tr>
<tr><td>Pixel Size</td><td>The tolerance of display pixel dimension should be within ±20% of the spec</td></tr>
<tr><td>Luminance</td><td>Refer to the spec or the reference sample</td></tr>
<tr><td>Color</td><td>Refer to the spec or the reference sample</td></tr>
</table>

■ CAUTIONS IN USING OLED MODULE

◆Precautions For Handling OLED Module:

1. OLED module consists of glass and polarizer. Pay attention to the following items when handling:
   i. Avoid drop from high, avoid excessive impact and pressure.
   ii. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead.
   iii. If the surface becomes dirty, breathe on the surface and gently wipe it off with a soft dry cloth. If it is terrible dirty, moisten the soft cloth with Isopropyl alcohol or Ethyl alcohol. Other solvents may damage the polarizer. Especially water, Ketone and Aromatic solvents.
   iv. Wipe off saliva or water drops immediately, contact the polarizer with water over a long period of time may cause deformation.
   v. Please keep the temperature within specified range for use and storage. Polarization degradation, bubble generation or polarizer peeling-off may occur with high temperature and high humidity.
   vi. Condensation on the surface and the terminals due to cold or anything will damage, stain or dirty the polarizer, so make it clean as the way of iii.
2. Do not attempt to disassemble or process the OLED Module.
3. Make sure the TCP or the FPC of the Module is free of twisting, warping and distortion, do not pull or bend them forcefully, especially the soldering pins. On the other side, the SLIT part of the TCP is made to bend in the necessary case.
4. When assembling the module into other equipment, give the glass enough space to avoid excessive pressure on the glass, especially the glass cover which is much more fragile.
5. Be sure to keep the air pressure under 120 kPa, otherwise the glass cover is to be cracked.
6. Be careful to prevent damage by static electricity:
   i. Be sure to ground the body when handling the OLED Modules.
   ii. All machines and tools required for assembling, such as soldering irons, must be properly grounded.
   iii. Do not assemble and do no other work under dry conditions to reduce the amount of static electricity generated. A relative humidity of 50%-60% is recommended.
   iv. Peel off the protective film slowly to avoid the amount of static electricity generated.
   v. Avoid to touch the circuit, the soldering pins and the IC on the Module by the body.
   vi. Be sure to use anti-static package.
7. Contamination on terminals can cause an electrochemical reaction and corrade the terminal circuit, so make it clean anytime.
8. All terminals should be open, do not attach any conductor or semiconductor on the terminals.
9. When the logic circuit power is off, do not apply the input signals.
10. Power on sequence: $V_{DD} \rightarrow V_{CC}$, and power off sequence: $V_{CC} \rightarrow V_{DD}$.
11. Be sure to keep temperature, humidity and voltage within the ranges of the spec, otherwise shorten Module’ s life time, even make it damaged.
12. Be sure to drive the OLED Module following the Specification and datasheet of IC controller, otherwise something wrong may be seen.

13. When displaying images, keep them rolling, and avoid one fixed image displaying more than 30 seconds, otherwise the residue image is to be seen. This is the speciality of OLED.

◆Precautions For Soldering OLED Module:

1. Soldering temperature : 260°C ± 10°C.
2. Soldering time : 3-4 sec.
3. Repeating time : no more than 3 times.
4. If soldering flux is used, be sure to remove any remaining flux after finishing soldering operation. (This does not apply in the case of a non-halogen type of flux.) It is recommended to protect the surface with a cover during soldering to prevent any damage due to flux spatters.

◆ Precautions For Storing OLED Module:

1. Be sure to store the OLED Module in the vacuum bag with dessicant.
2. If the Module can not be used up in 1 month after the bag being opened, make sure to seal the Module in the vacuum bag with dessicant again.
3. Store the Module in a dark place, do not expose to sunlight or fluorescent light.
4. The polarizer surface should not touch any other objects. It is recommended to store the Module in the shipping container.
5. It is recommended to keep the temperature between 0°C and 30°C , the relative humidity not over 60%.

◆ Limited Warranty

Unless relevant quality agreements signed with customer and law enforcement, for a period of 12 months from date of production, all products (except automotive products) TRULY will replace or repair any of its OLED modules which are found to be functional defect when inspected in accordance with TRULY OLED acceptance standards (copies available upon request). Cosmetic/visual defects must be returned to TRULY within 90 days of shipment. Confirmation of such date should be based on freight documents. The warranty liability of TRULY is limited to repair and/or replacement on the terms above. TRULY will not be responsible for any subsequent or consequential events.

◆Return OLED Module Under Warranty:

1. No warranty in the case that the precautions are disregarded.
2. Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects.

◆PRIOR CONSULT MATTER

1. For TRULY standard products , we keep the right to change material ,process … for improving the product property without any notice on our customer.
2. If you have special requirement about reliability condition, please let us know before you start the test on our samples.